

# Jae Hyeong Park

## List of Publications by Year in Descending Order

**Source:** <https://exaly.com/author-pdf/3216029/jae-hyeong-park-publications-by-year.pdf>  
**Version:** 2024-04-10

This document has been generated based on the publications and citations recorded by exaly.com. For the latest version of this publication list, visit the link given above.  
The third column is the impact factor (IF) of the journal, and the fourth column is the number of citations of the article.

141 papers	1,556 citations	21 h-index	33 g-index
210 ext. papers	1,913 ext. citations	1.9 avg, IF	4.51 L-index

#	Paper	IF	Citations
141	Acoustic Matching Layer Films Using B-Stage Thermosetting Polymer Resins for Ultrasound Transducer Applications. <i>IEEE Transactions on Ultrasonics, Ferroelectrics, and Frequency Control</i> , <b>2020</b> , 67, 2148-2154	3.2	3
140	Ultrathin Nanofibrous Membranes Containing Insulating Microbeads for Highly Sensitive Flexible Pressure Sensors. <i>ACS Applied Materials &amp; Interfaces</i> , <b>2020</b> , 12, 13348-13359	9.5	34
139	IMCs Microstructure Evolution Dependence of Mechanical Properties for Ni/Sn/Ni Micro Solder-Joints. <i>Materials</i> , <b>2020</b> , 13,	3.5	1
138	Low Temperature Transient Liquid Phase (TLP) Bonding using Eutectic Sn-In Solder Anisotropic Conductive Films (ACFs) for Flexible Ultrasound Transducer <b>2019</b> ,		2
137	A study on the resistivity and mechanical properties of modified nano-Ag coated Cu particles in electrically conductive adhesives. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2019</b> , 30, 9171-9183	2.1	21
136	A Study on the Conductive Particle Movements in Polyvinylidene Fluoride Anchoring Polymer Layer Anisotropic Conductive Films for 20- $\mu\text{m}$ Fine-Pitch Interconnection. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2019</b> , 9, 209-215	1.7	1
135	Piezoelectric Ceramics and Flexible Printed Circuits Interconnection Using Sn58Bi Solder Anisotropic Conductive Films for Flexible Ultrasound Transducer Assembly. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2019</b> , 9, 1897-1903	1.7	3
134	Effects of the Curing Properties and Viscosities of Non-Conductive Films (NCFs) on the Sn-Ag Solder Bump Joint Morphology and Reliability <b>2019</b> ,		1
133	. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2019</b> , 9, 2152-2159	1.7	2
132	The Effect of the Thermal Mechanical Properties of Nonconductive Films on the Thermal Cycle Reliability of 40- $\mu\text{m}$ Fine Pitch Cu-Pillar/Ni/SnAg Microbump Flip-Chip Assembly. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2019</b> , 9, 10-17	1.7	0
131	A Study on the Optimization of Anisotropic Conductive Films for Sn-3Ag-0.5Cu-Based Flex-on-Board Application at a 250 °C Bonding Temperature. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2018</b> , 8, 383-391	1.7	17
130	The Effect of the SnAg Solder Joint Morphology on the Thermal Cycle Reliability of 40 $\mu\text{m}$ Fine-Pitch Cu-Pillar/SnAg Micro Bump Interconnection <b>2018</b> ,		1
129	Fabrication and Characterization of Epoxy Molding Films (EMFs) for Wafer-Level and Panel-Level Fan Out Packages <b>2018</b> ,		2
128	A Study on the Curing Properties and Viscosities of Non-Conductive Films (NCFs) for Sn-Ag Solder Bump Flip Chip Assembly <b>2018</b> ,		3
127	A Study on the Nanofiber-Sheet Anisotropic Conductive Films (NS-ACFs) for Ultra-Fine-Pitch Interconnection Applications. <i>Journal of Electronic Materials</i> , <b>2017</b> , 46, 167-174	1.9	5
126	A Study on the Fabrication of Electrical Circuits on Fabrics Using Cu Pattern Laminated B-Stage Adhesive Films for Electronic Textile Applications <b>2017</b> ,		1
125	A Study on the Bonding Conditions and Nonconductive Filler Contents on Cationic Epoxy-Based Sn58Bi Solder ACFs Joints for Reliable Flex-on-Board Applications. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2017</b> , 7, 2087-2094	1.7	16

124	The Effect of Anisotropic Conductive Films Adhesion on the Bending Reliability of Chip-in-Flex Packages for Wearable Electronics Applications. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2017</b> , 7, 1583-1591	1.7	14
123	Moisture Effects on NCF Adhesion and Solder Joint Reliability of Chip-on-Board Assembly Using Cu Pillar/SnAg Microbump. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2017</b> , 7, 371-378	1.7	1
122	The Effect of Polymer Rebound on SnBi58 Solder ACFs Joints Cracks during a Thermo-Compression Bonding <b>2017</b> ,		1
121	Joint Morphologies and Failure Mechanisms of Anisotropic Conductive Films (ACFs) During a Power Handling Capability Test for Flex-On-Board Applications. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2016</b> , 6, 1820-1826	1.7	13
120	Thermo-Compression Bonding Using Non-conductive Films (NCFs) for 3-D TSV Micro-Bump Interconnection <b>2016</b> ,		1
119	A Study on the Cu-Rod Anisotropic Conductive Films (ACFs) for Flex-on-Fabric (FOF) Interconnections Using an Ultrasonic Bonding Method <b>2016</b> ,		3
118	Bending Properties of Anisotropic Conductive Films Assembled Chip-in-Flex Packages for Wearable Electronics Applications. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2016</b> , 6, 208-215	1.7	20
117	A Study on the Failure Mechanism and Enhanced Reliability of Sn58Bi Solder Anisotropic Conductive Film Joints in a Pressure Cooker Test Due to Polymer Viscoelastic Properties and Hydros swelling. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2016</b> , 6, 216-223	1.7	28
116	Effects of the Mechanical Properties of Polymer Resin and the Conductive Ball Types of Anisotropic Conductive Films on the Bending Properties of Chip-in-Flex Package. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2016</b> , 6, 200-207	1.7	10
115	A Study on the Double Layer Non Conductive Films (NCFs) for Fine-Pitch Cu-Pillar/Sn-Ag Micro-Bump Interconnection <b>2016</b> ,		5
114	Effects of Polymer Ball Size and Polyvinylidene Fluoride Nanofiber on the Ball Capture Rate for 100- $\mu\text{m}$ -Pitch Flex-on-Flex Assembly Using Anisotropic Conductive Films and Ultrasonic Bonding Method. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2016</b> , 6, 1127-1134	1.7	6
113	Effects of Cooling Processes and Silica Filler Contents of Solder ACFs (Anisotropic Conductive Films) on the Joints Reliability <b>2016</b> ,		2
112	Effect of Nanofiber Orientation on Nanofiber Solder Anisotropic Conductive Films Joint Properties and Bending Reliability of Flex-on-Flex Assembly. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2016</b> , 6, 1317-1329	1.7	19
111	Effects of PCB Pad Metal Finishes on the Cu-Pillar/Sn-Ag Micro Bump Joint Reliability of Chip-on-Board (COB) Assembly. <i>Journal of Electronic Materials</i> , <b>2016</b> , 45, 3208-3219	1.9	5
110	A Study on the Solder Ball Size and Content Effects of Solder ACFs for Flex-on-Board Assembly Applications Using Ultrasonic Bonding. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2015</b> , 5, 9-14	1.7	22
109	Effect of Flux Activators on the Solder Wettability of Solder Anisotropic Conductive Films. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2015</b> , 5, 3-8	1.7	6
108	Wafer level packages (WLPs) using B-stage non-conductive films (NCFs) for highly reliable 3D-TSV micro-bump interconnection <b>2015</b> ,		3
107	Ultra-thin chip-in-flex (CIF) technology using anisotropic conductive films (ACFs) for wearable electronics applications <b>2015</b> ,		3

106	Nanofiber Anisotropic Conductive Films (ACF) for Ultra-Fine-Pitch Chip-on-Glass (COG) Interconnections. <i>Journal of Electronic Materials</i> , <b>2015</b> , 44, 4628-4636	1.9	9
105	Effects of Curing Agent and Curing Temperature on Material Properties of Epoxy/BaTiO <sub>3</sub> Composite Embedded Capacitor Films. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2015</b> , 5, 451-459	1.7	2
104	Warpage Behavior and Life Prediction of a Chip-on-Flex Package Under a Thermal Cycling Condition. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2014</b> , 4, 1144-1151	1.7	0
103	Low-Temperature Curable Photo-Active Anisotropic Conductive Films (PA-ACFs). <i>Journal of Electronic Materials</i> , <b>2014</b> , 43, 3236-3242	1.9	3
102	A novel double layer NCF for highly reliable micro-bump interconnection <b>2014</b> ,		10
101	Effect of aligned nanofiber in nanofiber solder anisotropic conductive films (ACFs) on the solder ball movement for flex-on-flex (FOF) assembly <b>2014</b> ,		1
100	A study on the fine pitch chip interconnection using Cu/SnAg bumps and B-stage non-conductive films (NCFs) for 3D-TSV vertical interconnection <b>2014</b> ,		1
99	A novel fine pitch TSV interconnection method using NCF with Zn nano-particles <b>2014</b> ,		3
98	Analysis of 3D TSV Vertical Interconnection Using Pre-applied Nonconductive Films. <i>Journal of Electronic Materials</i> , <b>2014</b> , 43, 4214-4223	1.9	7
97	Low temperature fine pitch Flex-on-Flex (FOF) assembly using nanofiber Sn58Bi solder anisotropic conductive films (ACFs) and ultrasonic bonding method <b>2013</b> ,		5
96	Effects of ACF Bonding Parameters on ACF Joint Characteristics for High-Speed Bonding Using Ultrasonic Bonding Method. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2013</b> , 3, 177-182	1.7	5
95	Effects of nanofiber materials of nanofiber anisotropic conductive adhesives (nanofiber ACAs) for ultra-fine pitch electronic assemblies <b>2013</b> ,		1
94	Advancing Electronic Packaging Using Microsolder Balls: Making 25-nm Pitch Interconnection Possible. <i>IEEE Nanotechnology Magazine</i> , <b>2013</b> , 7, 24-30	1.7	4
93	Flux function added solder anisotropic conductive films (ACFs) for high power and fine pitch assemblies <b>2013</b> ,		9
92	Ultrasonic-Assisted Thermocompression Bonding Method of Solder Anisotropic Conductive Film Joints for Reliable Camera Module Packaging. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2013</b> , 3, 2156-2163	1.7	2
91	Effects of nanofiber on the electrical properties of anisotropic conductive adhesives (ACAs). <i>Journal of Nanoscience and Nanotechnology</i> , <b>2013</b> , 13, 351-5	1.3	4
90	Studies on the Thermal Cycling Reliability of BGA System-in-Package (SiP) With an Embedded Die. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2012</b> , 2, 625-633	1.7	17
89	Studies on the Polymer Adhesive Wafer Bonding Method Using Photo-Patternable Materials for MEMS Motion Sensors Applications. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2012</b> , 2, 1118-1127	1.7	8

88	Ultrasonic Bonding of Anisotropic Conductive Films Containing Ultrafine Solder Balls for High-Power and High-Reliability Flex-On-Board Assembly. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2012</b> , 2, 884-889	1.7	3
87	Effects of Conductive Particles on the Electrical Stability and Reliability of Anisotropic Conductive Film Chip-on-Board Interconnections. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2012</b> , 2, 359-366	1.7	9
86	Study on Fine Pitch Flex-on-Flex Assembly Using Nanofiber/Solder Anisotropic Conductive Film and Ultrasonic Bonding Method. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2012</b> , 2, 2108-2114	1.7	12
85	High performance encapsulant for light-emitting diodes (LEDs) by a sol-gel derived hydrogen siloxane hybrid. <i>Journal of Materials Chemistry</i> , <b>2012</b> , 22, 7954		60
84	Ultrasonic-assisted thermo-compression bonding method for high-performance solder anisotropic conductive film (ACF) joints <b>2012</b> ,		2
83	Micro-solder/adhesive hybrid joints for high-density, high-power, high-reliability, and reworkable module interconnection in mobile phones <b>2012</b> ,		2
82	Thermally resistant UV-curable epoxy/siloxane hybrid materials for light emitting diode (LED) encapsulation. <i>Journal of Materials Chemistry</i> , <b>2012</b> , 22, 8874		59
81	3D-TSV vertical interconnection method using Cu/SnAg double bumps and B-stage non-conductive adhesives (NCAs) <b>2012</b> ,		4
80	3D-TSV vertical interconnection method using Cu/SnAg double bumps <b>2012</b> ,		2
79	Vertically aligned nickel nanowire/epoxy composite for electrical and thermal conducting material <b>2012</b> ,		2
78	High productivity and damage-free ultrasonic anisotropic conductive film (ACF) bonding for touch screen panel (TSP) assemblies <b>2012</b> ,		1
77	Low temperature curable anisotropic conductive films (ACFs) with photo-active curing agent (PA-ACFs) <b>2012</b> ,		3
76	A study on the intermetallic growth of fine-pitch Cu pillar/SnAg solder bump for 3D-TSV interconnection <b>2012</b> ,		2
75	Wafer-Level Packages Using Anisotropic Conductive Adhesives (ACAs) Solution for Flip-Chip Interconnections. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2011</b> , 1, 792-797	1.7	4
74	Effect of Ag Addition on the Ripening Growth of $\text{Cu}_{60}\text{Sn}_{40}$ Grains at the Interface of Sn-xAg-0.5Cu/Cu During a Reflow. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2011</b> , 1, 1939-1946	1.7	8
73	Investigation of various photo-patternable adhesive materials and their processing conditions for MEMS sensor wafer bonding <b>2011</b> ,		3
72	High-speed flex-on-board assembly method using anisotropic conductive films (ACFs) combined with room temperature ultrasonic (US) bonding for high-density module interconnection in mobile phones <b>2011</b> ,		5
71	Nanofiber anisotropic conductive adhesives (ACAs) for ultra fine pitch chip-on-film (COF) packaging <b>2011</b> ,		12

70	Effect of fine solder ball diameters on intermetallic growth of Sn-Ag-Cu solder at Cu and Ni pad finish interfaces during thermal aging <b>2011</b> ,		3
69	A study on the 3D-TSV interconnection using wafer-level non-conductive adhesives (NCAs) <b>2011</b> ,		2
68	A Study of Hygrothermal Behavior of ACF Flip Chip Packages With Moiré Interferometry. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2010</b> , 33, 215-221		12
67	Effects of fine size lead-free solder ball on the interfacial reactions and joint reliability <b>2010</b> ,		11
66	High speed touch screen panels (TSPs) assembly using anisotropic conductive adhesives (ACAs) vertical ultrasonic bonding method <b>2010</b> ,		2
65	Effect of Pd addition on ultra-fine pitch Au wire/Al pad interface <b>2010</b> ,		5
64	Effects of the Degree of Cure on the Electrical and Mechanical Behavior of Anisotropic Conductive Films. <i>Journal of Electronic Materials</i> , <b>2010</b> , 39, 410-418	1.9	7
63	Reduced Temperature Coefficient of Capacitance (TCC) of Embedded Capacitor Films (ECFs) for Organic Substrates using SrTiO <sub>3</sub> and Multifunctional Epoxy. <i>Journal of Electronic Materials</i> , <b>2010</b> , 39, 1358-1363	1.9	4
62	Thermal cycling reliability of Cu/SnAg double-bump flip chip assemblies for 100 $\mu$ m pitch applications. <i>Journal of Applied Physics</i> , <b>2009</b> , 105, 013522	2.5	5
61	Characterization of epoxy/BaTiO <sub>3</sub> composite embedded capacitors for high frequency behaviors <b>2009</b> ,		1
60	Effects of Heating Rate on Material Properties of Anisotropic Conductive Film (ACF) and Thermal Cycling Reliability of ACF Flip Chip Assembly. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2009</b> , 32, 339-346		4
59	Ultrasonic Bonding Using Anisotropic Conductive Films (ACFs) for Flip Chip Interconnection. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , <b>2009</b> , 32, 241-247		15
58	Nonconductive Films (NCFs) With Multifunctional Epoxies and Silica Fillers for Reliable NCFs Flip Chip on Organic Boards (FCOBs). <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , <b>2009</b> , 32, 65-73		4
57	Effects of Anisotropic Conductive Film Viscosity on ACF Fillet Formation and Chip-On-Board Packages. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , <b>2009</b> , 32, 74-80		16
56	Effects of Thermal Cycling on Material Properties of Nonconductive Pastes (NCPs) and the Relationship Between Material Properties and Warpage Behavior During Thermal Cycling. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2008</b> , 31, 559-565		3
55	Adhesion and Reliability of Anisotropic Conductive Films (ACFs) Joints on Organic Solderability Preservatives (OSPs) Metal Surface Finish. <i>Journal of Electronic Materials</i> , <b>2008</b> , 37, 1003-1011	1.9	5
54	A Study on the Thermal Reliability of Cu/SnAg Double-Bump Flip-Chip Assemblies on Organic Substrates. <i>Journal of Electronic Materials</i> , <b>2008</b> , 37, 1832-1842	1.9	13
53	Theoretical Prediction and Experimental Measurement of the Degree of Cure of Anisotropic Conductive Films (ACFs) for Chip-On-Flex (COF) Applications. <i>Journal of Electronic Materials</i> , <b>2008</b> , 37, 1580-1590	1.9	8



52	Screen printable epoxy/BaTiO <sub>3</sub> embedded capacitor pastes with high dielectric constant for organic substrate applications. <i>Journal of Applied Polymer Science</i> , <b>2008</b> , 110, 798-807	2.9	24
51	Wafer Level Packages (WLPs) using Pre-Applied Anisotropic Conductive Films (ACFs) <b>2007</b> ,		3
50	Study of the Formation of Bubbles in Rigid Substrate-Flexible Substrate Bonding Using Anisotropic Conductive Films and the Bubble Effects on Anisotropic Conductive Film Joint Reliability. <i>Journal of Electronic Materials</i> , <b>2007</b> , 36, 56-64	1.9	5
49	Effects of the Functional Groups of Nonconductive Films (NCFs) on Material Properties and Reliability of NCF Flip-Chip-On-Organic Boards. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2007</b> , 30, 464-471		11
48	Wafer-Level Flip Chip Packages Using Preapplied Anisotropic Conductive Films (ACFs). <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , <b>2007</b> , 30, 221-227		7
47	Effect of Sb addition in Sn-Ag-Cu solder balls on the drop test reliability of BGA packages with electroless nickel immersion gold (ENIG) surface finish <b>2007</b> ,		1
46	Non-Conductive Films (NCFs) with Multi-Functional Epoxies and Silica Fillers for Reliable NCFs Flip Chip On Organic Boards (FCOB) <b>2007</b> ,		1
45	Effect of electroless Ni/Au UBM thickness on mechanical and electromigration reliability of Pb-free solder joints <b>2007</b> ,		1
44	Electromigration of Pb-Free Solder Flip Chip Using Electroless Ni-P/Au UBM <b>2007</b> ,		5
43	Cu/SnAg Double Bump Flip Chip Assembly as an Alternative of Solder Flip Chip on Organic Substrates for Fine Pitch Applications <b>2007</b> ,		7
42	Effect of electromigration on mechanical shear behavior of flip chip solder joints. <i>Journal of Materials Research</i> , <b>2006</b> , 21, 698-702	2.5	21
41	Epoxy/BaTiO <sub>3</sub> (SrTiO <sub>3</sub> ) Composite Films and Pastes For High Dielectric Constant and Low Tolerance Embedded Capacitors in Organic Substrates <b>2006</b> ,		8
40	Epoxy/BaTiO <sub>3</sub> /sub 3/ composite films and pastes for high dielectric constant and low-tolerance embedded capacitors fabrication in organic substrates. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , <b>2005</b> , 28, 297-303		16
39	Effects of Cu contents in Pb-free solder alloys on interfacial reactions and bump reliability of Pb-free solder bumps on electroless Ni-P under-bump metallurgy. <i>Journal of Electronic Materials</i> , <b>2005</b> , 34, 80-90	1.9	33
38	A study on the temperature dependence of epoxy/BaTiO <sub>3</sub> composite embedded capacitor films. <i>Journal of Electronic Materials</i> , <b>2005</b> , 34, 1264-1269	1.9	7
37	Comparison of theoretical predictions and experimental values of the dielectric constant of epoxy/BaTiO <sub>3</sub> composite embedded capacitor films. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2005</b> , 16, 77-84	2.1	70
36	Frequency and Temperature Dependence of Dielectric Constant of Epoxy/BaTiO <sub>3</sub> Composite Embedded Capacitor Films (ECFs) for Organic Substrate <b>2005</b> ,		3
35	Flip chip interconnection with anisotropic conductive adhesives for RF and high-frequency applications. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2005</b> , 28, 789-796		21

34	Effects of Pd addition on Au stud bumps/Al pads interfacial reactions and bond reliability. <i>Journal of Electronic Materials</i> , <b>2004</b> , 33, 1210-1218	1.9	20
33	Highly reliable flip-chip-on-flex package using multilayered anisotropic conductive film. <i>Journal of Electronic Materials</i> , <b>2004</b> , 33, 76-82	1.9	23
32	Contraction stress build-up of anisotropic conductive films (ACFs) for flip-chip interconnection: Effect of thermal and mechanical properties of ACFs. <i>Journal of Applied Polymer Science</i> , <b>2004</b> , 93, 2634-2641	2.8	12
31	Exothermic reaction induced eutectic Pb-Sn solder ball melting in the underfill curing process. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2004</b> , 27, 172-176		
30	A study on interfacial reactions between electroless Ni-P under bump metallization and 95.5Sn-4.0Ag-0.5Cu alloy. <i>Journal of Electronic Materials</i> , <b>2003</b> , 32, 548-557	1.9	55
29	Effects of Cu/Al intermetallic compound (IMC) on copper wire and aluminum pad bondability. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2003</b> , 26, 367-374		140
28	Highly reliable non-conductive adhesives for flip chip CSP applications. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , <b>2003</b> , 26, 150-155		28
27	Comparison of interfacial reactions and reliabilifies of Sn3.5Ag, Sn4.0Ag0.5Cu, and Sn0.7Cu solder bumps on electroless Ni-P UBMs <b>2003</b> ,		4
26	Under bump metallurgy study for Pb-free bumping. <i>Journal of Electronic Materials</i> , <b>2002</b> , 31, 478-487	1.9	10
25	Studies of electroless nickel under bump metallurgySolder interfacial reactions and their effects on flip chip solder joint reliability. <i>Journal of Electronic Materials</i> , <b>2002</b> , 31, 520-528	1.9	38
24	Stresses in electroless Ni-P films for electronic packaging applications. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2002</b> , 25, 169-173		10
23	Grain Morphology of Intermetallic Compounds at Solder Joints. <i>Journal of Materials Research</i> , <b>2002</b> , 17, 597-599	2.5	39
22	UbBM (under bump metallization) study for Pb-free electroplating bumping : interface reaction and electromigration <b>2002</b> ,		7
21	Effect of nonconducting filler additions on ACA properties and the reliability of ACA flip-chip on organic substrates. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2001</b> , 24, 24-32		34
20	Reduced thermal strain in flip chip assembly on organic substrate using low CTE anisotropic conductive film. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , <b>2000</b> , 23, 171-176		25
19	The effect of reduction ratio of hot rolling on texture and secondary recrystallization of MA 754 plate. <i>Journal of Materials Science Letters</i> , <b>1999</b> , 18, 1645-1648		2
18	. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>1998</b> , 21, 226-234		102
17	The effect of the oxidation of Cu-base leadframe on the interface adhesion between Cu metal and epoxy molding compound. <i>IEEE Transactions on Advanced Packaging</i> , <b>1997</b> , 20, 167-175		34



16	Low Temperature Oxidation of Cu-Base Leadframe and Cu/EMC Interface Adhesion. <i>Materials Research Society Symposia Proceedings</i> , <b>1996</b> , 445, 275	1
15	Design and understanding of anisotropic conductive films (ACFs) for LCD packaging	1
14	Wafer level package using pre-applied anisotropic conductive films (ACFs) for flip-chip interconnections	1
13	Effect of compressive stresses in anisotropic conductive films (ACFs) on contact resistance of flip chip joint	4
12	Novel epoxy/BaTiO/sub 3/ composite embedded capacitor films embedded in organic substrates	4
11	The effect of T/sub g/ on thermo-mechanical deformation and reliability of adhesive flip chip assemblies during temperature cycling	5
10	Interfacial reactions and bump reliability of various Pb-free solder bumps on electroless Ni-P UBMs	1
9	Effects of the functional groups of nonconductive films (NCFs) on materials properties and reliability of NCF flip-chip-on-organic boards	1
8	Low tolerance epoxy/BaTiO/sub 3/ composite embedded capacitor films (ECFs)	2
7	Analytical approach to evaluate shear stress in flip chip interconnection using NCA/ACF	4
6	High reliable non-conductive adhesives for flip chip CSP applications	1
5	New anisotropic conductive adhesives for low cost and reliable flip chip on organic substrates applications	3
4	Effect of non-conducting filler additions on anisotropic conductive adhesives (ACAs) properties and the reliability of ACAs flip chip on organic substrates	2
3	Pb-free bumping technology and UBM (under bump metallurgy)	1
2	Relationships between suspension formulations and the properties of BaTiO/sub 3//epoxy composite films for integral capacitors	1
1	Effects of particle size on dielectric constant and leakage current of epoxy/barium titanate (BaTiO/sub 3/) composite films for embedded capacitors	2